

Technical Data Sheet

FeedBond® FP-1725-B5

Low cure temperature Cure Conductive Adhesive

Introduction:

FeedBond®FP-1725-B5 is an electrically conductive adhesive. It is designed for low temperature curing in oven.

Characteristics:

- Low cure temperature
- One component
- Excellent flexibility
- Low viscosity, apply for use in automatic die attach equipment

UNCURED PROPERTIES		TEST DESCRIPTION	TEST METHOD
Density	3.5 g/cc	Pycnometer	FT-P001
Appearance	Silver		
Viscosity @ 25°C	10,000 cps	Brookfield DV-III/CP-51 @ 5rpm	FT-P006
Thixotropic Index @ 25°C	4.5	Brookfield DV-III/CP-51 Visc. @ 0.5rpm/Visc. @ 5rpm	FT-P008
Grind	< 25µm	Grind meter	FT-P026
Work Life @ 25°C	48 hrs	25% increase in visc. @ 5rpm	FT-P024
Shelf Life@ -40°C	6 months		FT-P018
CURE CONDITION		TEST DESCRIPTION	TEST METHOD
Standard Cure Condition in oven		90min @110°C	
		120min @120°C	
Die Shear Strength @ 25°C	>5 kg/die	80mil × 80mil Si die on Ag LF	FT-M012

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PHYSIOCHEMICAL PROPERTIES- POST CURE	TEST DESCRIPTION	TEST METHOD
Glass Transition Temperature (Tg) 60°C Coefficient of Thermal Expansion Below Tg(α_1) 103ppm/°C Above Tg(α_2) 246 ppm/°C Storage Modulus @25°C 2742MPa @150°C 11MPa @250°C 16MPa	DMA 3 Point Bending Mode TMA Expansion Mode Dynamic Mechanical Thermal Analysis using <1.6mm thick specimen	FT-M014 FT-M016 FT-M019A
THERMAL ELECTRICAL PROPERTIES- POST CURE	TEST DESCRIPTION	TEST METHOD
Volume resistivity <0.0008 $\Omega \cdot \text{cm}$	4-point probe	FT-P017
Thermal conductivity 3.0 W/mK	Hot Disk	FT-P022

p.s. The tables shown above are typical values only. If you need to write a specification, please request our current Standard Release Specification.

Instruction

Thawing

Place the container to stand vertically for 30min ~90min. **DO NOT** open the container before adhesive reaches ambient temperature to prevent the moisture condensation. Any moisture that collects on the thawed container should be removed prior to use. Adhesives that appear to have separated should not be used.

Storage

Adhesive should be stored @ -40°C. The shelf life of the material is only valid when the material has been stored at the correct storage condition.

Availability

FeedBond adhesives are packaged in syringes or pots per customer specification. For the details, please contact our Customer Service or sales department.

Storage temp.	-35°C~-42°C	-18°C~-22°C	0°C~5°C	18°C~28°C
shelf life	6 months	3 months	1 month	2 days